





Debris-Free 100 - 200mm Wafer Marking

The Industry-Leading SoftMark Solution

SigmaClean's Class 1 cleanroom compatibility and ultra-stable patented diode-pumped laser has helped to make it the industryleading solution for cost-efficient, highly-readable soft marking of 100 mm to 200 mm wafers for identification and traceability.

Patented SuperSoftMark[®] Technology

SigmaClean's proprietary super softmark technology, along with it's patented diode-pumped laser, enables it to deliver debris-free soft marking, and allows the system to be installed in customer cleanrooms for high-volume production.

High Performance with Greater Control

SigmaClean combines a highperformance laser system with best-in-class system-level closedloop control and automated system data logging. All laser performance data is accurately logged to SPC levels of mark quality.



SEMI-Compliant Wafer Marking

ESI's WaferMark system are fully compliant with SEMI standards for wafer marking: T7, M12 and M13.

SigmaClean can place multiple mark groups at any orientation on the wafer surface, within a 25mm band around the wafer's circumference.

System Specifications

Dot Matrix Hardmark

0.02 particles/cm, 0.17

<1.1 major to minor axis

125 wph single pulse, 5x8

dot matrix, 12 characters

particle size measured over

(straight line or arc

marking)

5 mm area

ratio

0 wph

50 µm +/- 10%

2.6 µm + 0.4 µm

Marking Performance

Marking Modes

SuperSoftMark® Process

Dot Diameter

Dot Roundness

Dot Depth

Throughput

Throughput Edge

Handling (option)

Material Polished, non-coating, pure Si wafers

Marking Fonts (Standard)

9 x17 Single Density Dot Matrix 10x18 Double Density Dot Matrix 5x9 SEMI-OCR T1-93 SEMI Specs BC-412 Bar Code T7 2D Data Matrix Checksum Function (user selectable)

Mark Char Mark Field Mark Location

Mark Repeatability

Character Formation

Laser Optics

Туре

Wavelength Pulse to Pulse Stability Optics Spot Size Depth 80 char/ group max 50x50mm after wafer aligned Within a 25 mm band around wafer circumference +/- 0.125 µm in X & Y relative to primary fiducial Meets SEMI M12-92

Acousto-optic Q-switched, TEM₀₀ ND: YLF diode-pumped laser 1053 nm <0.5% at 1 kHz Flat field focusing lens 50, 60 or 70 μm 2.5 to 5.0 μm

Wafer Handling

Wafer Size Alignment Water Transport

I/O Ports

Utility Requirements

Electrical Process Vacuum

Mark Point Exhaust

Ambient Conditions Air Cooled System Dimensions

Weight

Workstation Enclosure

PC Configuration

Intel Xeon-E3-1275 V3 3.5 KHz 4-Core CPU Windows 7 Pro SP1, 32 Bit 4GB DDR3 1333MHz ECC Memory (2x2GB) (3) PCI; (1) PCIe x1; (2) PCIe x16 slots (4) 10/100/1000T LAN Ports (4) USB 3.0; (9) USB 2.0 Ports (2) RS232 ports - Includes Adapter Plates (2) Intel 20GB 2.5" Solid State Drives 2-Drawer drive carrier for 2.5" drives LG 24X DVD/DL Drive

Control System

Keyboard and flat panel display Menu-driven "fill in the blank" software Multiple job file storage capability Fault and error logging capabilities System diagnostic indicators displayed on front panel and electronic console Four-color programmable signal tower

Certification

CE Mark SEMI S2, S8, S14



Ask an Expert! For facilities guidelines requirements or more information, please contact your local ES office or visit www.esi.com.

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Optical high-resolution wafer aligner

Two fixed FOUP carrier load ports

20 Hg to 25 Hg diameter press-lock

Pick and place robot arm with single end

200-240 VAC, single phase, 50/60Hz, 23FLA

20 CFM (560 I/min) flow rate max 1.25 inch

Static Charge: 197 V/cm (550 V/in) max

Temp: 12.8 - 27° (55-80 °F) 78" x 64.6" x 47.4" [HxWxD] (1981.2mm x

EFEM: 1480 lb (671 kg) Mark Enclosure:

Stainless steel, ISO Class 5 clean room

100 - 200mm

effector

connection

(32 mm) diameter port

1641mm x 1204 mm)

compatible with ISO Class 2

1145 lbs (519 kg)

mini-environment